

- (51) International Patent Classification:

H05K 7/20 (2006.01)
- (21) International Application Number:

PCT/US2024/051309
- (22) International Filing Date:

15 October 2024 (15.10.2024)
- (25) Filing Language:

English
- (26) Publication Language:

English
- (30) Priority Data:

63/544,470 17 October 2023 (17.10.2023) US
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- (81) Designated States (unless otherwise indicated, for every kind of national protection available):

AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available):

ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ,

(54) Title: SYSTEMS AND METHODS FOR TWO-PHASE IMMERSION COOLING

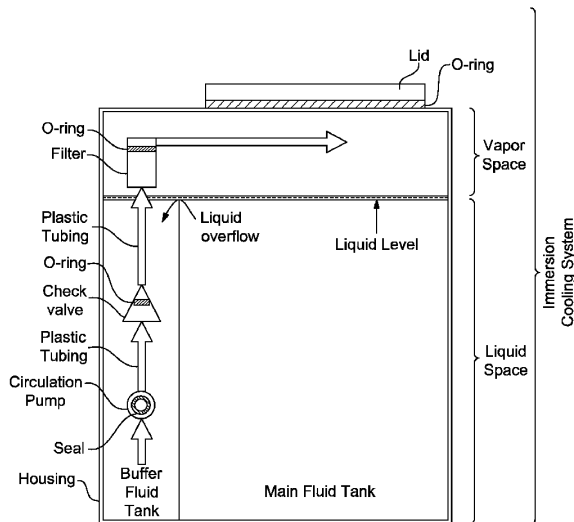


FIG. 1

(57) Abstract: An immersion cooling system comprising an apparatus containing a heat transfer fluid comprising E-1,1,1,2,2,5,5,6,6,6-decafluoro-3-hexene and an electronic device, wherein the materials used in the apparatus and the electronic device are made of materials compatible with the heat transfer fluid. There is also provided a method in which the immersion cooling system is used to cool an electronic device.

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DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,
LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))